P-CHANNEL ENHANCEMENT MODE POWER MOSFET

MTB40P06Q8

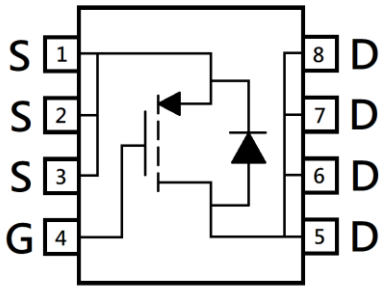
BV_{DSS}	-60V
I_D @ T_A=25°C, V_{GS}=-10V	-6.2A
R_{DSON}@V_{GS}=-10V, I_D=-6.2A	41.7mΩ(typ)
R_{DSON}@V_{GS}=-4.5V,I_D=-5A	48.3mΩ(typ)

Features

- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

Equivalent Circuit

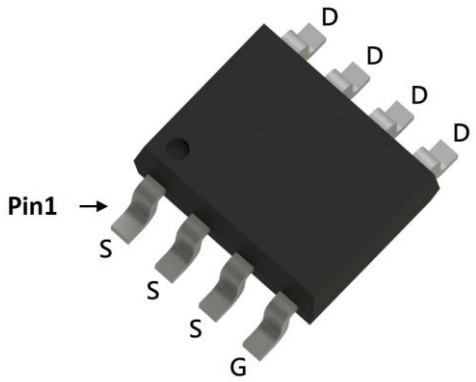
MTB40P06Q8



G : Gate S : Source D : Drain

Outline

SOP-8



Ordering Information

Device	Package	Shipping
MTB40P06Q8-0-TF-G	SOP-8 (Pb-free lead plating and halogen-free package)	4000 pcs / tape & reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, TF : 4000 pcs/tape & reel, 13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Breakdown Voltage		BV_{DSS}	-60	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current (Note 1)	T_A=25°C, V_{GS}=-10V	I_D	-6.2	A
	T_A=70°C, V_{GS}=-10V		-5	
Pulsed Drain Current (Note 2)		I_{DM}	-40	
Single Pulse Avalanche Current @ L=0.1mH		I_{AS}	-13	
Single Pulse Avalanche Energy @ L=1mH		E_{AS}	49	mJ
Total Power Dissipation (Note 1)	T_A=25°C	P_D	3.1	W
	T_A=70°C		2	
Operating Junction and Storage Temperature Range		Tj ; Tstg	-55~+150	°C

Note : 1.Surface mounted on FR-4 board, t≤10sec. The value in any given application depends on the user's specific board design.
2.Pulse width ≤300μs, Duty Cycle≤2%

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{\theta JC}$	25	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{\theta JA}$	40 (Note)	

Note : Surface mounted on 1 in² copper pad of FR-4 board, pulse width≤10s.

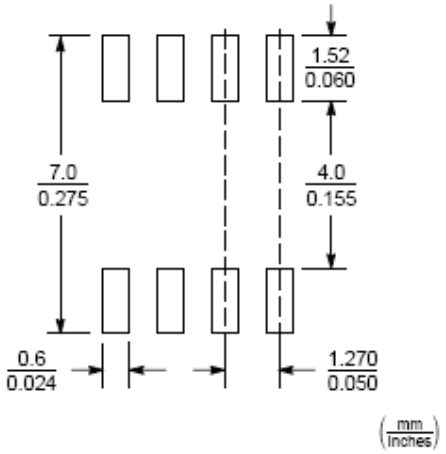
Electrical Characteristics (Tj=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-60	-	-	V	V_{GS}=0V, I_D=-250μA
$V_{GS(th)}$	-1	-	-2.5		V_{DS}=V_{GS}, I_D=-250μA
I_{GSS}	-	-	±100	nA	V_{GS}=±20V, V_{DS}=0V
I_{DSS}	-	-	-1	μA	V_{DS}=-48V, V_{GS}=0V
*$R_{DS(ON)}$	-	41.7	54.5	mΩ	I_D=-6.2A, V_{GS}=-10V
	-	48.3	65		I_D=-5A, V_{GS}=-4.5V
*G_{FS}	-	15.3	-	S	V_{DS}=-5V, I_D=-6.2A
Dynamic					
Ciss	-	2094	-	pF	V_{DS}=-30V, V_{GS}=0V, f=1MHz
Coss	-	90	-		
Crss	-	68	-		
*$t_{d(ON)}$	-	11.4	-	ns	V_{DD}=-30V, I_D=-6.2A, V_{GS}=-10V, R_G=3Ω
*t_r	-	17.8	-		
*$t_{d(OFF)}$	-	63.4	-		
*t_f	-	9.2	-		

*Qg	-	38	-	nC	V_{DS}=-30V, V_{GS}=-10V, I_D=-6.2A
*Qgs	-	8.6	-		
*Qgd	-	4	-		
Rg	-	8.6	-	Ω	f=1MHz
Source Drain Diode					
*I_S	-	-	-4.2	A	
*I_{SM}	-	-	-16		
*V_{SD}	-	-0.79	-1	V	V_{GS}=0V, I_S=-1A
*trr	-	15.2	-	ns	I_F=6.2A, dI_F/dt=100A/μs
*Qrr	-	12.4	-	nC	

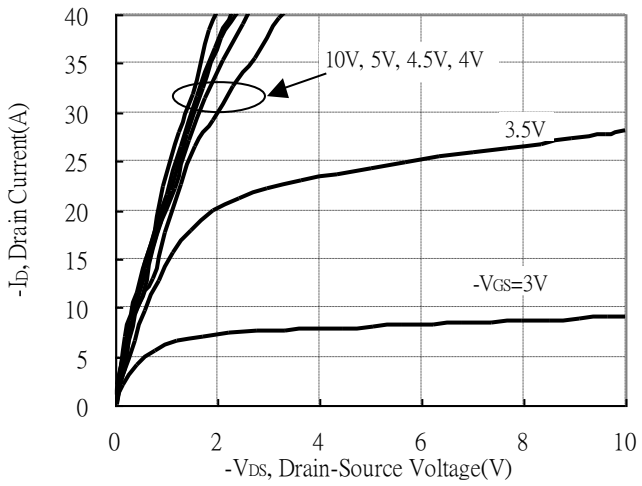
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended Soldering Footprint

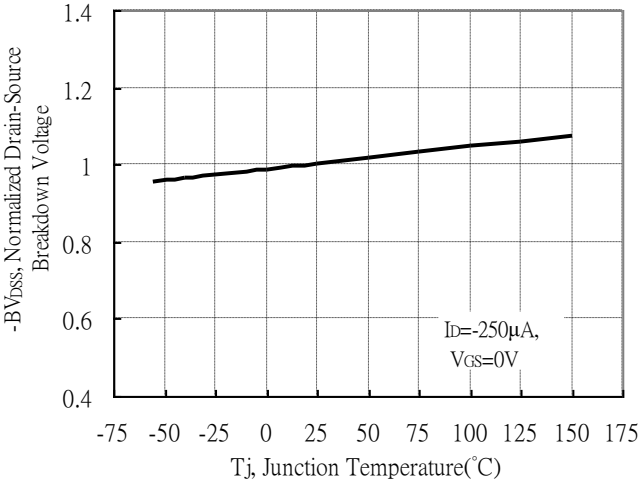


Typical Characteristics

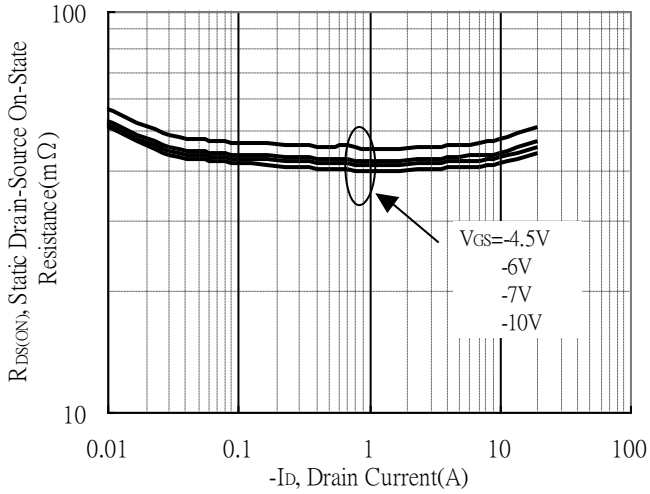
Typical Output Characteristics



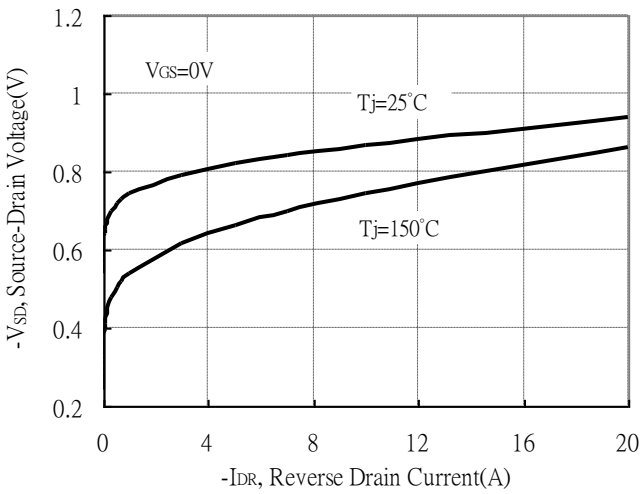
Brekdown Voltage vs Temperature



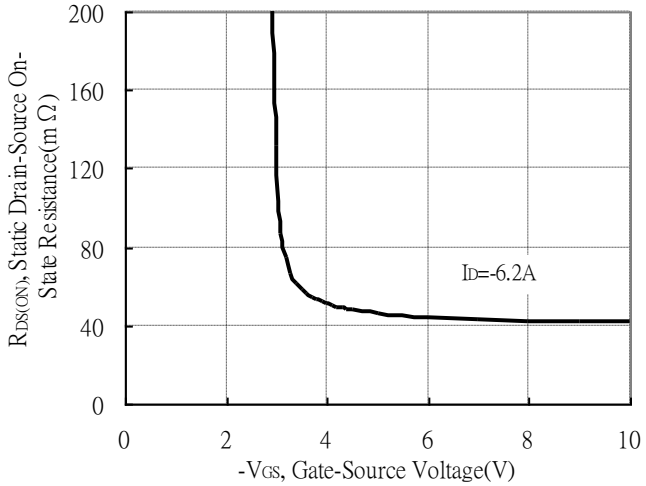
Static Drain-Source On-State resistance vs Drain Current



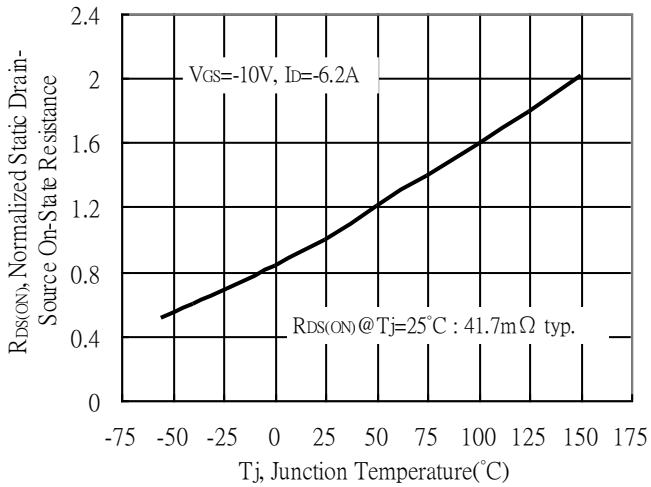
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

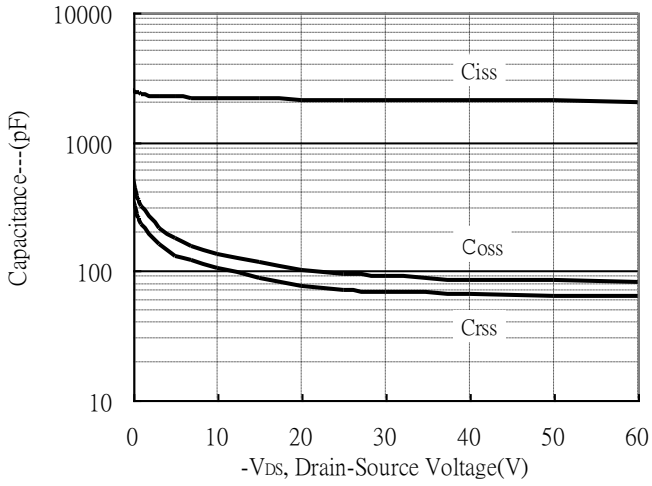


Drain-Source On-State Resistance vs Junction Tempearture

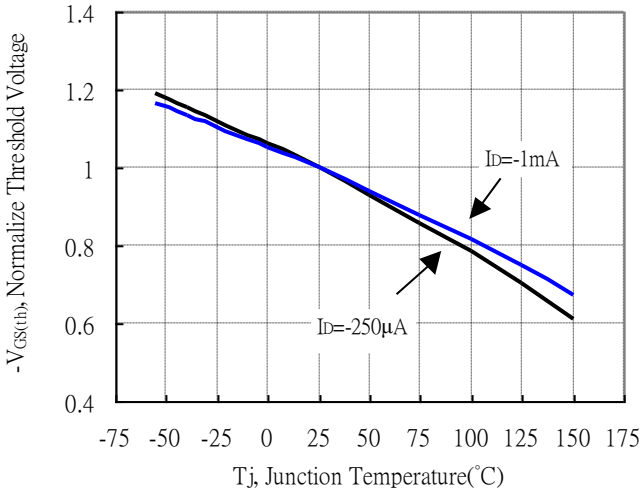


Typical Characteristics(Cont.)

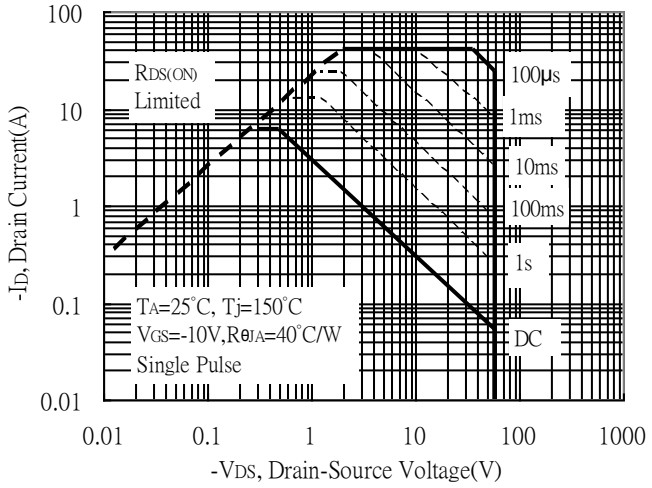
Capacitance vs Drain-to-Source Voltage



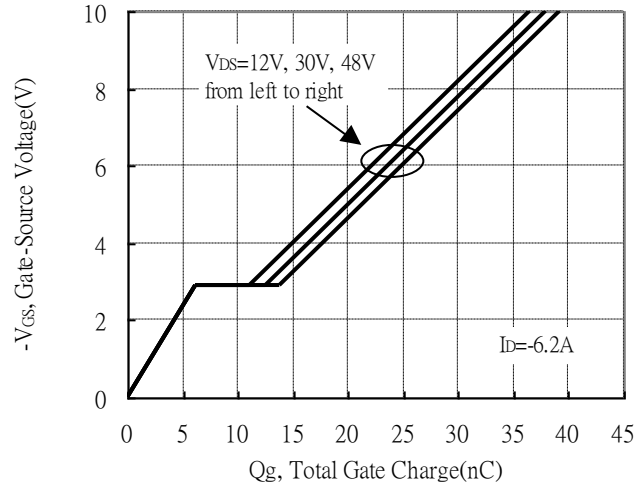
Threshold Voltage vs Junction Tempearture



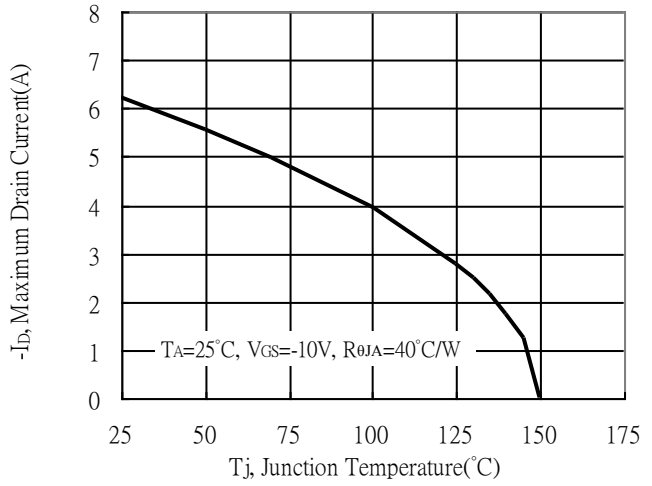
Maximum Safe Operating Area



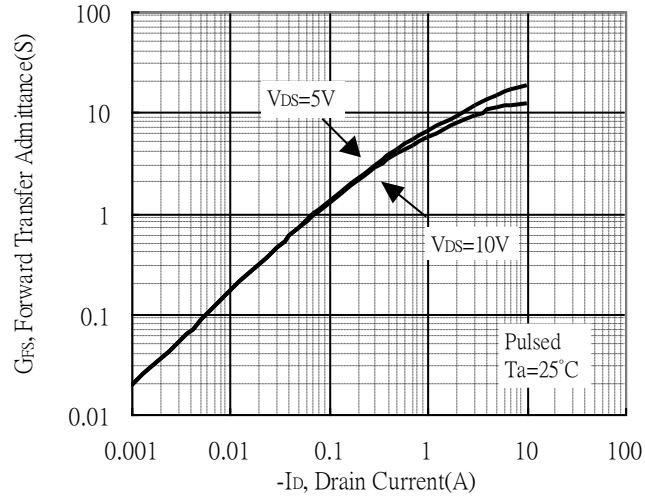
Gate Charge Characteristics



Maximum Drain Current vs Junction Temperature

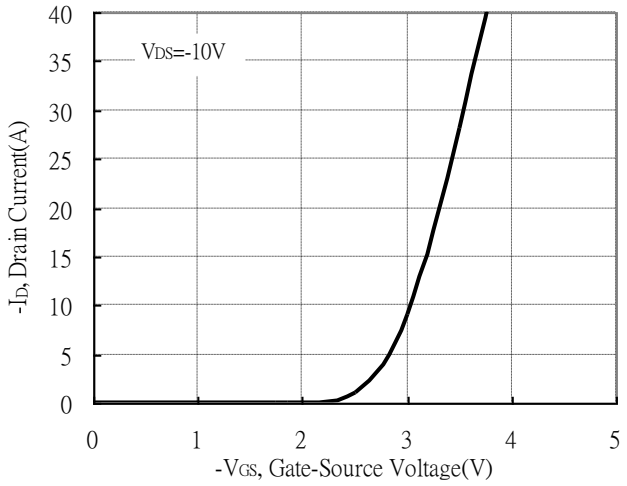


Forward Transfer Admittance vs Drain Current

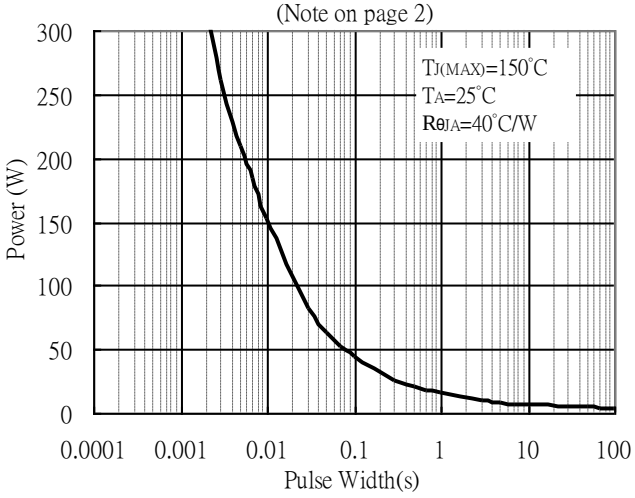


Typical Characteristics(Cont.)

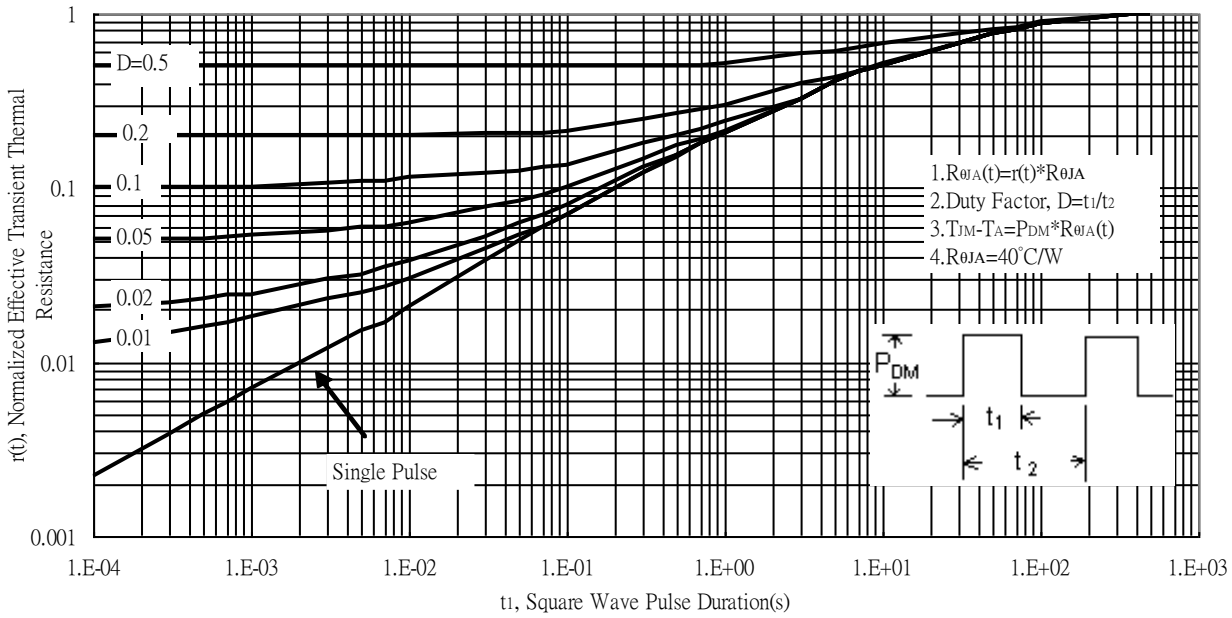
Typical Transfer Characteristics



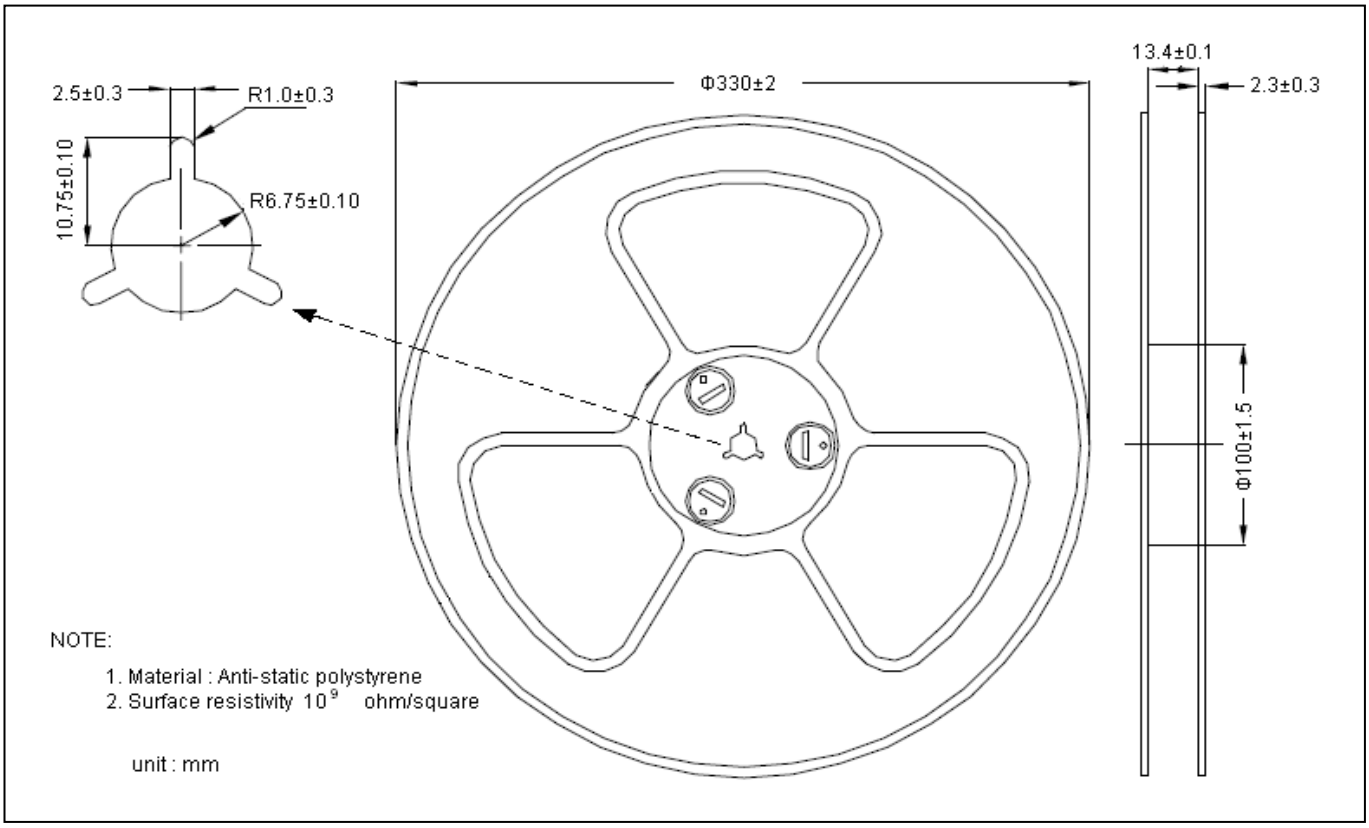
Single Pulse Power Rating, Junction to Ambient
(Note on page 2)



Transient Thermal Response Curves



Reel Dimension

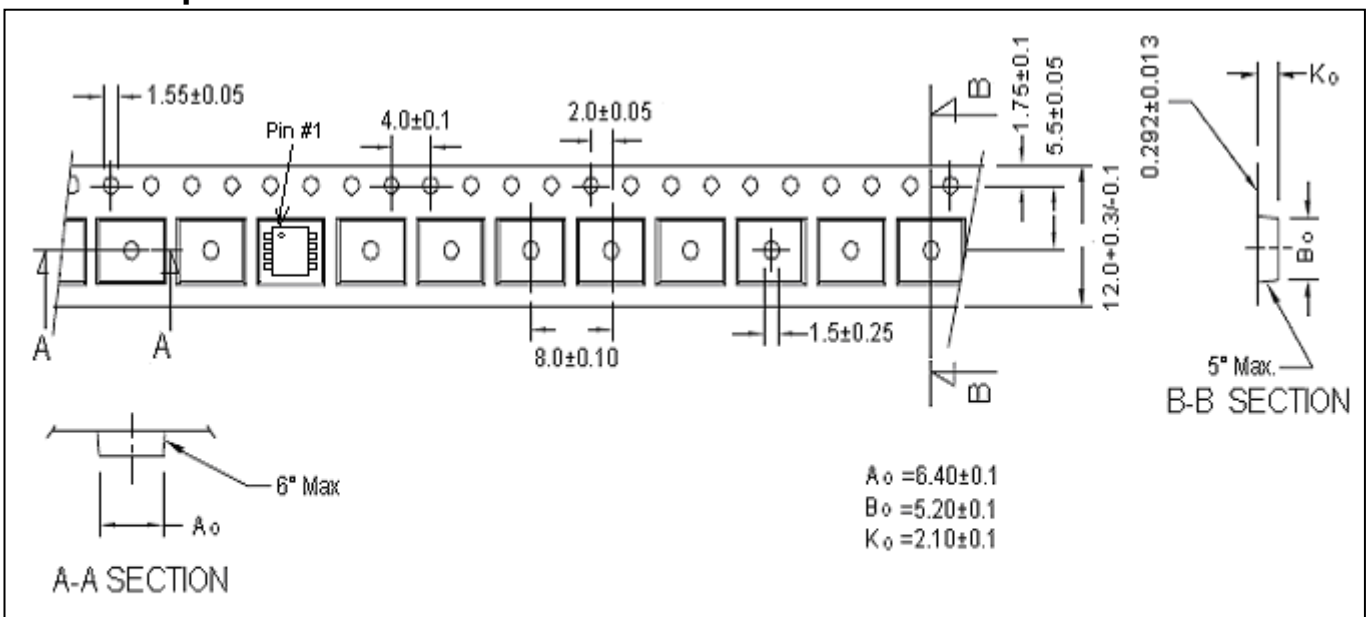


NOTE:

1. Material : Anti-static polystyrene
2. Surface resistivity 10^9 ohm/square

unit : mm

Carrier Tape Dimension



Ao =6.40±0.1
Bo =5.20±0.1
Ko =2.10±0.1

Notes:

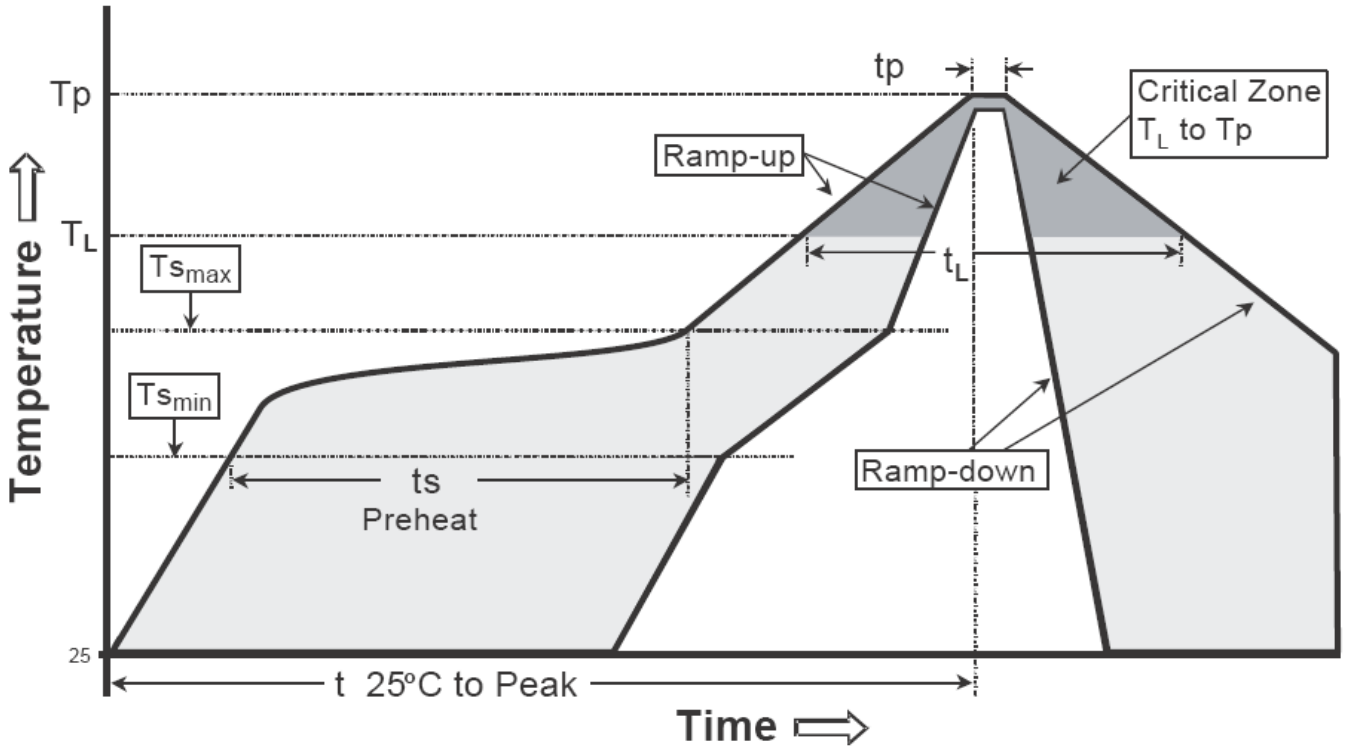
1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Uni : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

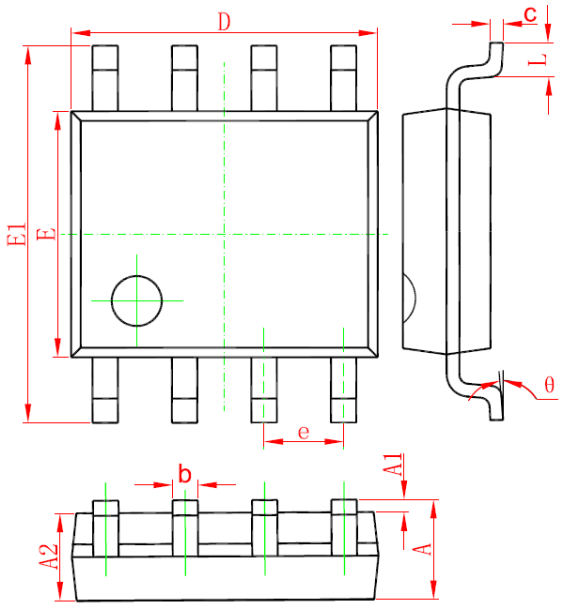
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time(ts $_{min}$ to ts $_{max}$)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

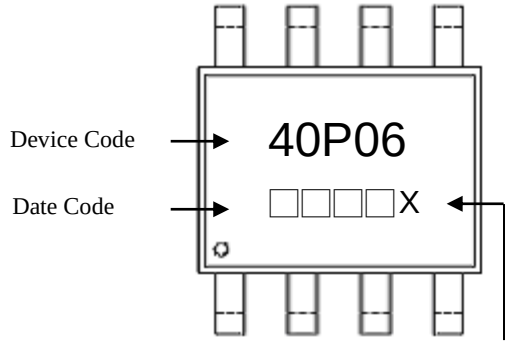
Note : All temperatures refer to topside of the package, measured on the package body surface.

SOP-8 Dimension



8-Lead SOP-8 Plastic Package
CYStek Package Code: Q8

Marking:



Assembly site code :
Blank→ site 1
G →site 2

Date Code(counting from left to right) :
1st code: year code, the last digit of Christian year
2nd code : month code, Jan→A, Feb→B, Mar→C, Apr→D
May→E, Jun→F, Jul→G, Aug→H, Sep→J,
Oct→K, Nov→L, Dec→M
3rd and 4th codes : production serial number, 01~99

*: Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069	E	3.800	4.000	0.150	0.157
A1	0.100	0.250	0.004	0.010	E1	5.800	6.200	0.228	0.244
A2	1.350	1.550	0.053	0.061	e	*1.270		*0.050	
b	0.330	0.510	0.013	0.020	L	0.400	1.270	0.016	0.050
c	0.170	0.250	0.006	0.010	θ	0°	8°	0°	8°
D	4.700	5.100	0.185	0.200					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.